

REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0			2023 20/04	

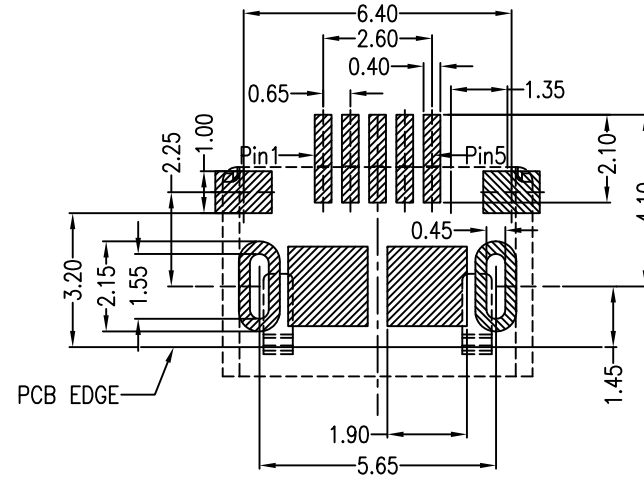
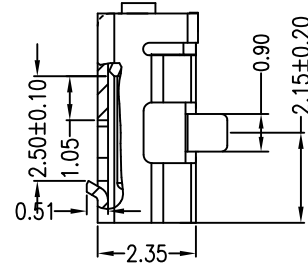
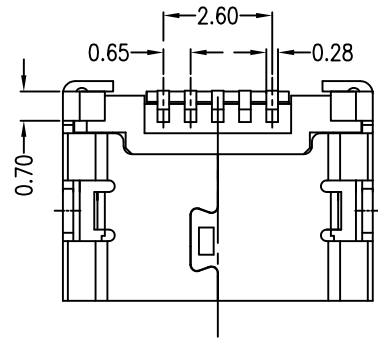
Note:

1. Material:

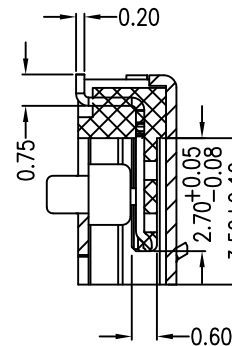
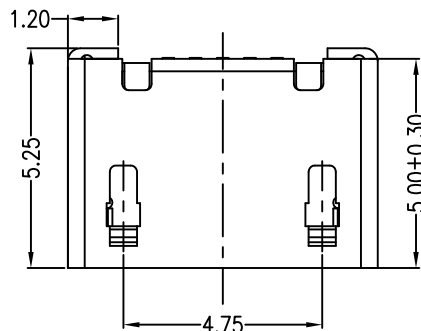
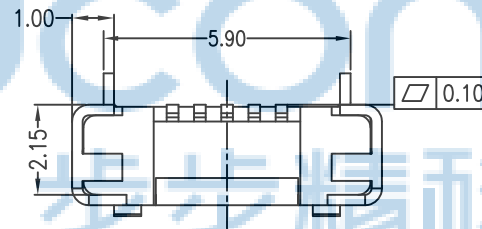
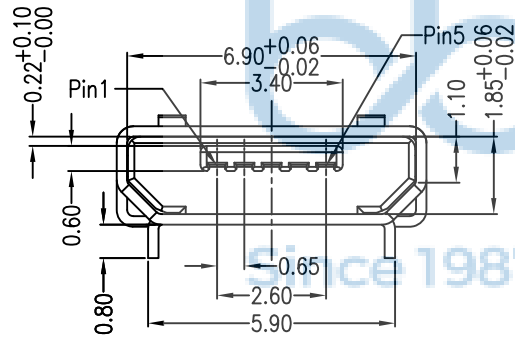
- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy, t=0.20mm
- 1.3 Shell: sus304, t=0.25mm / C2680

2. Specification:

- 2.1 Current rating: 1, 5PIN 1.8A Max/2, 3, 4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -30° C~80° C



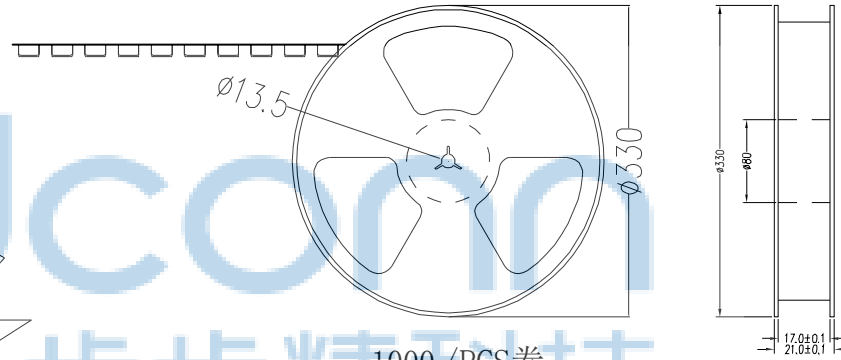
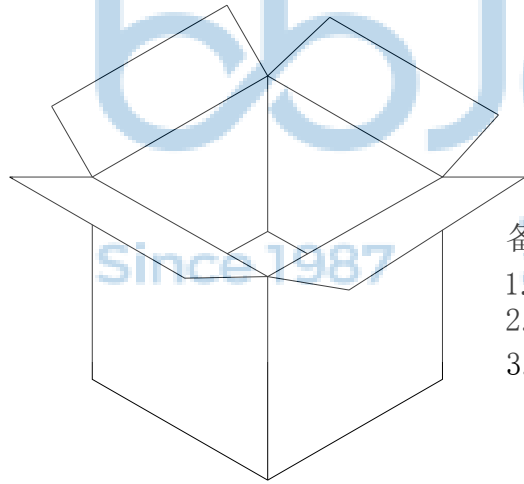
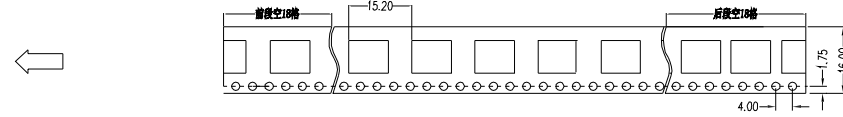
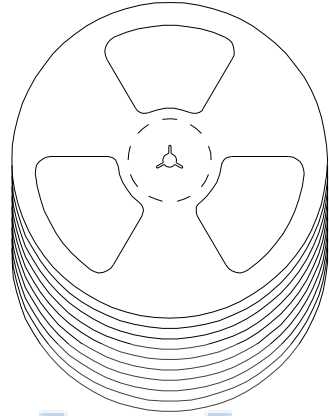
RECOMMENDED PCB LAYOUT PCB图仅供参考



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APPD.	JM_Zheng	23/05'02	P.J. NO.: MC.01.22-11-1003		SIZE: A4 DRW NO.:			
CHKD.	LYX	23/05'02	FINISH: SEE NOTES		MAT'L.: SEE NOTES			
PDWG.NO:	0113-1	DR.	SGF	23/05'02	SCALE: N/A	REV.: A3	UNIT: mm	PAGE: 1/1

深圳市步步精科技有限公司

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- 备注： 1000 /PCS卷
1. 包装数量: 1000 /PCS/卷, 10卷/箱或15卷/箱。
 2. 包装袋长度: 每卷前后各空10-20个空格, 中间包装。
 3. 材质:
 - 载体: 聚丙烯 (PS), 阻抗 $10^{6-9} \Omega$
 - 上带: 聚乙烯 (PET), 阻抗 $10^{6-11} \Omega$
 - 卷盘: 聚苯乙烯。

纸箱规格: 345*345*23MM
纸箱规格: 345*345*35MM



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CORPORATION AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		NAME: MICRO-5P 内插无柱 L=5.25 固定脚距5.65 平口 铜壳 雾锡	
APPD.	JM_Zheng 23/05'02	PJ. NO.: MC.01.22-11-1003	
CHKD.	LYX 23/05'02	SIZE: A4 DRW NO.:	
PDWG.NO: 0113-1	DR. SGF 23/05'02	FINISH: SEE NOTES MAT'L.: SEE NOTES	
		SCALE: N/A REV.: A3 UNIT: mm PAGE: 1/1	